FIG.1A

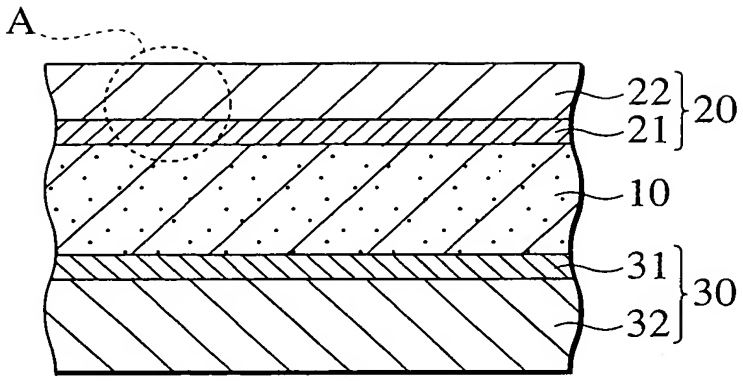

FIG.1B

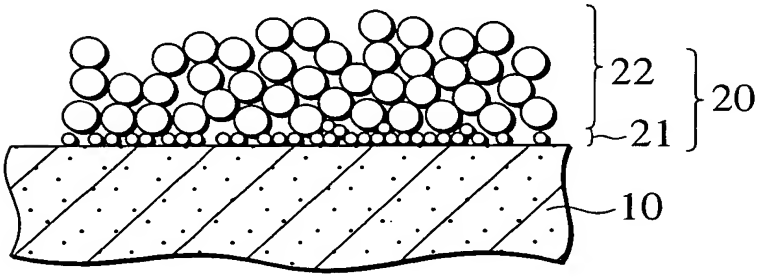

FIG.2

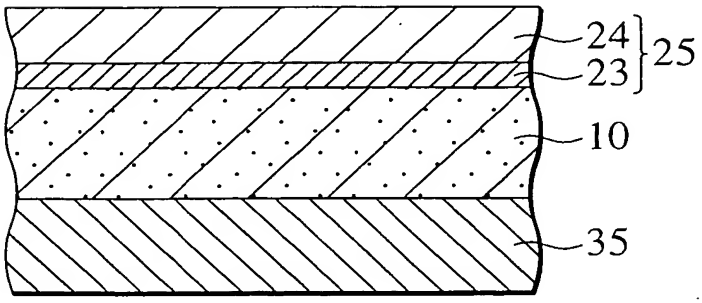

FIG.3A

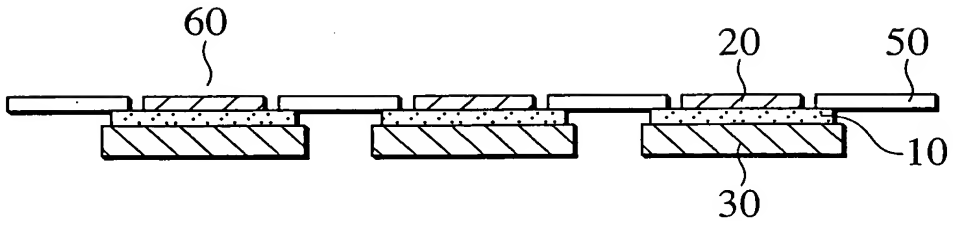

FIG.3B

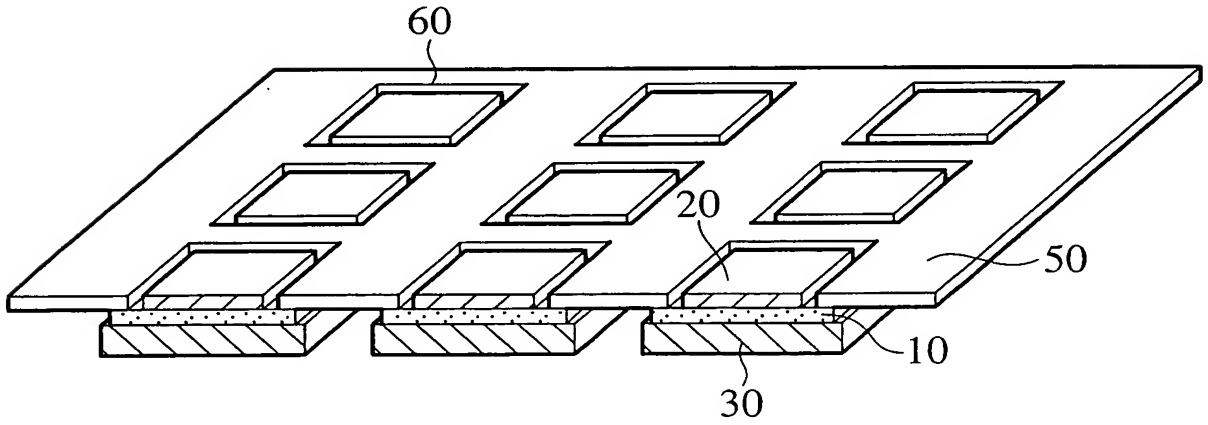

FIG.4A

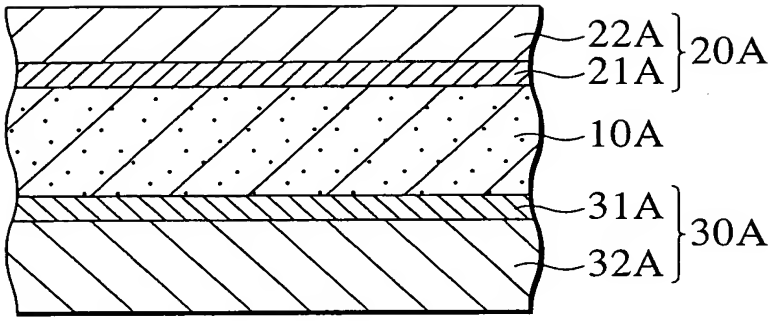

FIG.4B

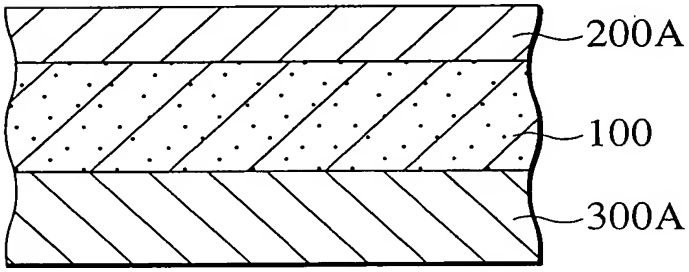

FIG.4C

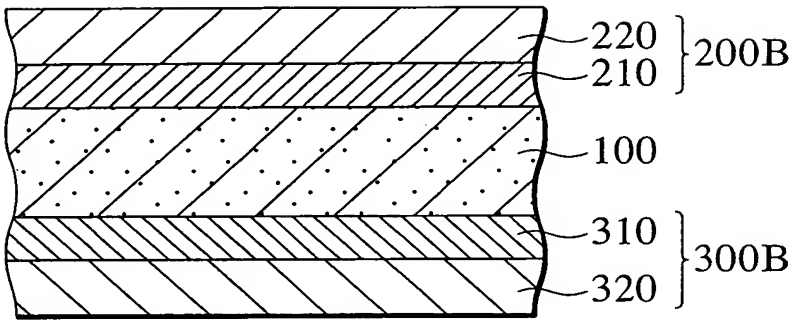

FIG.4D

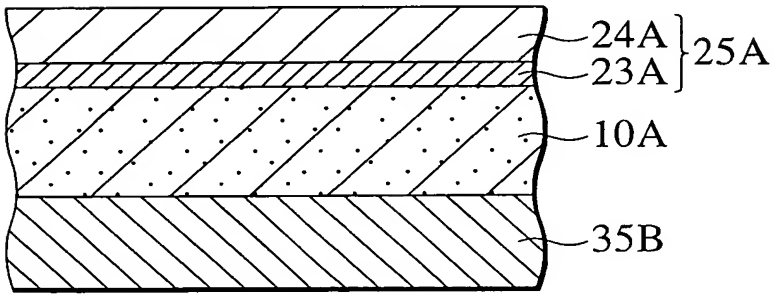

FIG.5

Table. 1

	Air electrode (Ag)		Fuel electrode (Ni)		Peeling property	Cell property (i=0.4A/cm^2 hour)
	Lower layer	Upper layer	Lower layer	Upper layer		
Example 1	Sputtering film : 50 nm	Splayed film : 15 μm	Sputtering film : 50 nm	Splayed film : 35 μm	OK	0.130W/cm^2
Comparative example 1	——	Splayed film : 15 μm	——	Splayed film : 35 μm	OK	0.12W/cm^2
Example 2	Splayed film : 0.1 μm	Splayed film : 15 μm	Splayed film : 0.1 μm	Splayed film : 35 μm	OK	0.127W/cm^2
Comparative example 2	——	Splayed film : 15 μm	——	Splayed film : 35 μm	×	0.123W/cm^2
Comparative example 3	Sputtering film : 2 μm	Splayed film : 15 μm	Sputtering film : 2 μm	Splayed film : 35 μm	×	0.11W/cm^2

*) The lower layer and the upper layer in the air electrode are an adhering cathode layer and an electricity collecting cathode layer respectively.

*) The lower layer and the upper layer in the fuel electrode are an adhering anode layer and an electricity collecting anode layer respectively.

FIG.6

Tabl. 2

Example No	Electrical collecting cathode layer		Adhering cathode layer						Cell resistance (Ω)
	Material	Particle diameter	Material		Method	Baking temperature (℃)	Adhesion strength	Resistance (Ω)	
Example 3	LSC	5 μm	Ag	1 μm	Sputtering	800	○	0.05	2.3
Example 4	LSC	5 μm	Bismuth oxide	1 μm	EB deposition	800	○	0.11	2.5
Example 5	LSC	5 μm	Ag+LSC	0.1 μm	Sputtering	850	○	0.07	2.3
Example 6	LSC	5 μm	Bismuth oxide+ glass frit	3 μm	Screen printing	900	○	0.15	2.8
Comparative example 4	LSC	5 μm	Nothing	—	—	1100	○	—	350
Comparative example 5	LSC	5 μm	Nothing	—	—	800	×	—	12.5
Comparative example 6	LSC	5 μm	Ag	10 μm	Sputtering	850	○	0.21	56.2
Comparative example 7	LSC	5 μm	Bismuth oxide+ glass frit	2 μm	Screen printing	500	×	0.18	3.5